

MEC1-120-02-F-D-A MEC1-130-02-F-D-A MEC1-140-02-L-D **MEC1 SERIES**

(1.00 mm) .0394"

EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material: Black LCF

Contact Material:

Plating: Sn or Au over 50 μ"

(1.27 μm) Ni

Operating Temp Range:
-55 °C to +125 °C

Current Rating:

2.2 A per pin (2 adjacent pins powered)

Voltage Rating: 300 VAC

Insertion Depth:

(5.84 mm) .230" to (8.13 mm) .320" **RoHS Compliant:**

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (05-20) (0.15 mm) .006" max (30-70)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Locking Clip (Manual placement required)
- Other platings

Contact Samtec.

Important Note:

Samtec recommends that pads on the mating board be Gold plated.

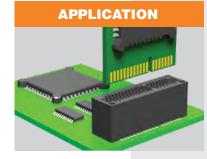
Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.

Some sizes, styles and options are non-standard, non-returnable

Mates with:

(1.60 mm) .062" card



.062" card

HIGH-SPEED CHANNEL PERFORMANCE

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

02

PLATING OPTION

OTHER OPTION

Optional Alignment pin

05, 08, 20, 30, 40, 50, 60, 70

POSITIONS

PER ROW

= Gold flash on contact, Matte tin on tail

> = 10 µ" (0.25 µm) Gold on contact Matte Tin on tail

-NP = No Polarizatio<u>n</u> (05, 08, 20 & 30 positions only)

Leave Blank for polarization

–A = Alignment Pin metal or plastic at Samtec discretion.

Mates with

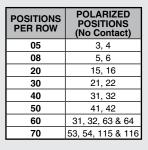
(1.60 mm)

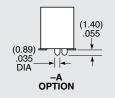
= (7.87 mm) .310" DIA Polyimide film Pick & Place Pad

-TR = Tape & Reel (05-60 only)

→	(No. of Positions + 2) x (1.00) .03937 + (2.54) .100	←
(6.99) .275		<u>+</u>
<u>_</u>		1.83) .072









.006

(8.51)